Tputty™ 910

1-Part Dispensable Gap Filler

PRODUCT DESCRIPTION

At 9 W/m-K thermal conductivity, Tputty™ 910 is at the forefront of thermal performance for a one-part dispensable gap filler. This dispensable gap filler minimizes stress on components during assembly while providing the reliability of a traditional thermal pad. Tputty™ 910 is a soft, compliant, high thermal conductivity dispensable gap filler providing the lowest thermal resistance and highest reliability available.

FEATURES AND BENEFITS

- Thermal Conductivity 9.1W/mK
- Dispensable and Compliant
- Easily reworkable
- Ideal for large gaps
- Meets ROHS and REACH requirements

APPLICATIONS

- Telecom base stations
- Graphic chips
- Microprocessors
- High-power automotive electronic controls

MAIN PROPERTIES

TYPICAL PROPERTIES	VALUE	TEST METHOD
Composition	Ceramic filled dispensable silicone	
Color	Light red	Visual
Flow rate (75cc taper tip, 90psi)	75 g/min	Laird Method
Shelf Life	6 months	Laird Method
Thermal Conductivity	9.1 W/mK	Hot Disk
Density	3.2 g/cc	Helium Pycnometer
Minimum Bond Line Thickness	180 µm	Laird Method
Operating Temperature Range	-40°C to 180°C	
UL Flammability Rating	V-0 (pending)	UL 94
Dielectric Breakdown Voltage	6kV/mm	ASTM D149
Dielectric constant (1MHz)	10	ASTM D150
Volume Resistivity	$3.2x10^{17}$ Ohm.cm	ASTM D2240
Thermal resistance at 1.5mm, 80°C/40psi	1.76 °C.cm²/W	ASTM D5470

PACKAGING

PACKAGING SIZE	FILL VOLUME	FILL WEIGHT
30cc syringe	30cc	96g
75cc EFD cartridge	56cc	179g
180cc EFD cartridge	159cc	509g
300cc alu cartridge	300cc	960g
1 gallon pail	4062cc	13kg

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